

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A compact fluorescent lamp package comprising:

a screw base for electrically connecting said lamp package to an electrical socket which is capable of receiving a screw base of an ordinary incandescent lamp, said screw base including an open end and a closed end and a wall surrounding said closed end to provide an enclosure around a space;

a multi-chip module including a complete ballast circuit formed on a circuit board contained inside said screw base and electrically connected to said screw base to receive power through said screw base;

a thermally conductive body disposed around said ballast circuit within said screw base, and thermally connecting said wall of said screw base to said ballast circuit directly, whereby said screw base may dissipate heat generated by said ballast circuit; and

a fluorescent lamp extending away from said screw base and operatively connected to said ballast circuit.

2. (Previously Presented) A compact fluorescent lamp package according to claim 1, further comprising a diffuser cover disposed around said fluorescent lamp and directly connected to said screw base to provide said lamp package with an appearance of an ordinary incandescent lamp.

3. Canceled

4. (Previously Presented) A compact fluorescent lamp package according to claim 1, wherein said screw base is an Edison screw base.

5. (Original) A compact fluorescent lamp package according to claim 1, wherein said multi-chip module is formed on a single circuit board.

6. (Original) A compact fluorescent lamp package according to claim 5, wherein said ballast circuit includes elements disposed on both sides of said circuit board.

7. (Previously Presented) A compact fluorescent lamp package according to claim 6, wherein said elements include design dependent electronic components and design independent electronic components, said design dependent electronic components being disposed on one side of said circuit board and said design independent electronic components being disposed on another opposing side of said circuit board.

8. (Previously Presented) A compact fluorescent lamp package according to claim 6, wherein said design dependent electronic components include a filter inductor, a resonant inductor, a capacitor, and said design independent electronic components include power switching devices.

9. (Previously Presented) A compact fluorescent lamp package according to claim 1, wherein said thermally conductive body is a thermal epoxy which is disposed in said space in said base for mechanical stability and thermal management.

10. (Original) A compact fluorescent lamp package according to claim 1, wherein said multi-chip module comprises a circuit board that has a perimeter that generally follows the contour of the wall of said base.

11. (Original) A compact fluorescent lamp package according to claim 1, wherein said multi-chip module is formed on a generally circular circuit board.

12. (Original) A compact fluorescent lamp package according to claim 1, wherein said multi-chip module is formed on a generally rectangular circuit board.

13. (Original) A compact fluorescent lamp package according to claim 1, wherein said wall of said base serves as a connector for connecting said lamp to one pole of a power line, and said closed end of said base includes a connector insulated from said wall serving as a connector for connecting to another pole of said power line.

14. (Previously Presented) A compact fluorescent lamp package according to claim 1, wherein said multi-chip module is electrically connected to said wall of said screw base via a first electrical wire and electrically connected to a connector disposed on said end of said screw base via a second electrical wire.

15. (Original) A compact fluorescent lamp package according to claim 1, wherein said fluorescent lamp is connected to said multi-chip module via respective filament terminals.

16. (Previously Presented) A compact fluorescent lamp package according to claim 1, wherein said multi-chip module includes a circuit board having at least one heatsink disposed on one major surface thereof, said heatsink being thermally connected through said circuit board to a heat-generating electronic component.

Claims 17-37 (canceled).

38. (Currently Amended) A compact fluorescent lamp comprising:
a screw base configured to be received in an electrical socket, said screw base having a bottom portion and an annular wall extending from said bottom portion and disposed around a space, said screw base being configured for external electrical connection;
a circuit board having two opposing surfaces disposed in said space;

an electronic ballast circuit including a plurality of electronic components, said components being disposed on both surfaces of said circuit board, said electronic ballast being electrically connected to said screw base to receive power;

a thermally conductive body disposed within said screw base and in direct thermal contact with said electronic ballast circuit and said annular wall of said base thereby thermally connecting said ballast circuit and said screw base;

a fluorescent lamp operatively connected to said electronic ballast; and

a diffuser cover directly attached to said screw base and surrounding said fluorescent lamp without an intermediate compartment disposed therebetween.

39. (Previously Presented) A compact fluorescent lamp according to claim 38, wherein said screw base is an Edison screw base.

40. (Previously Presented) A compact fluorescent lamp according to claim 38, wherein said diffuser cover is shaped like an ordinary incandescent light bulb.

41. (Previously Presented) A compact fluorescent lamp according to claim 38, wherein said electronic ballast circuit is disposed entirely within said screw base.

42. (Previously Presented) A compact fluorescent lamp according to claim 38, wherein said thermally conductive body comprises a thermal epoxy.